

REFURBISHED STEPPER

Thin Film Head and Air Bearing Surfaces

The model 1700MVS is the world's most widely used thin film head (TFH) lithography tool for high-volume manufacturing.

Incorporating an advanced machine vision system and customized software specifically designed for rowbar level processing, the 1700MVS recognizes and automatically aligns to preexisting features, thus eliminating the need for special targets

Design simplicity makes the 1700MVS a highly reliable, easy-to-operate, and easy-to-maintain system. Its low initial investment cost and low operating costs also enable it to provide tremendous cost-of-ownership benefits.

The UltraStep 1700MVS features include:

- * 1.4 micron resolution
- * 3 x 5 x 0.090 or 5 x 5 x 0.090 inch reticle
- * Machine Vision Alignment
- * Automatic site-by-site alignment
- * Air probe electronic focus detection
- * Wafer thickness compensator
- * Broadband exposure (g/h -line)
- * Flexible field size
- * High wafer plane irradiance
- * Large depth of focus
- * Multiple fields per reticle

SPECIFICATIONS:

Wafer Size:	3", 4", 5", 6", or 8"
Loader Type:	Automation / Manual
Computer:	HP 362 w/Hard Disk
Machine Vision:	Cognex
Uniformity:	3.0 %
Depth of Focus:	7.0 ums @ 1.4um lines
Maximum Square:	18 x 18 mm
Maximum Aspect:	39 x 11.4 mm
Maximum Area:	34.2 x 13.6 mm
Reticle Size:	3" x 5" x 0.090"

Stepper Equipment Inc
4151 Citrus Ave Rocklin, CA. . 95677
Office 916-632-1031 Fax 916-632-1018
E-mail info@stepequipment.com
Web www.stepequipment.com

Ultratech Model 1700 Machine Vision System

Serial Number 1305
Manufactured June, 1998
Minimum resolution: 1.4 micron
Full field or Rowbar Illumination



HP362 and Cognex computers

Manufacturing label

